

Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 8900	Ablestik 8900	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Reliability Qualification Plan for LFCSP Package with Non-conductive Die Attach Epoxy at STATS ChipPAC China (SCC)

QUALIFICATION PLAN			
Test	Conditions	Sample Size	Expected Completion Date
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	April 2014
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	April 2014
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	April 2014
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	April 2014

*Preconditioned per JEDEC/IPC J-STD-020